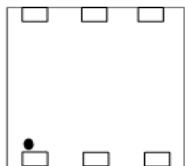
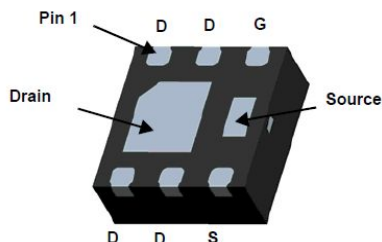


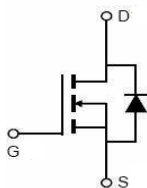
N-Channel Enhancement Mode Field Effect Transistor



Marking and pin assignment



DFN22-6L



Product Summary

- V_{DS} 20V
- I_D 20A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $< 8\text{ mohm}$
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) $< 13\text{ mohm}$
- $R_{DS(ON)}$ (at $V_{GS}=1.8V$) $< 20\text{ mohm}$

General Description

- Trench Power LV MOSFET technology
- High Power and current handing capability

Applications

- PWM application
- Load switch

Ordering Information (Example)

PREFERED P/N	PACK	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
JCWT8CN2ES6	DFN2*2-6	T8CN	3000	45000	180000	7" reel

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	20	V
Gate-source Voltage	V_{GS}	± 12	V
Drain Current	$T_A=25^\circ\text{C}$ @ Steady State	20	A
	$T_A=70^\circ\text{C}$ @ Steady State	12	
Pulsed Drain Current ^A	I_{DM}	30	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	1.5	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	$-55\sim+150$	$^\circ\text{C}$

■ Electrical Characteristics (T_j=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V, T _C =25℃			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±10V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	0.45	0.62	1.2	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 4.5V, I _D =6.8A	6		8	mΩ
		V _{GS} = 2.5V, I _D =3.0A	9		13	
		V _{GS} = 1.8V, I _D =2.5A	15		20	
Diode Forward Voltage	V _{SD}	I _S =6A, V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				6	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHZ		1600		pF
Output Capacitance	C _{oss}			640		
Reverse Transfer Capacitance	C _{rss}			239		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =4.5V, V _{DS} =10V, I _D =6A		9.2		nC
Gate Source Charge	Q _{gs}			1.7		
Gate Drain Charge	Q _{gd}			2.9		
Turn-on Delay Time	t _{D(on)}	V _{GS} =4.5V, V _{DD} =10V, R _L =1.5Ω, R _{GEN} =3Ω		12		ns
Turn-on Rise Time	t _r			52		
Turn-off Delay Time	t _{D(off)}			17		
Turn-off Fall Time	t _f			10		

A. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

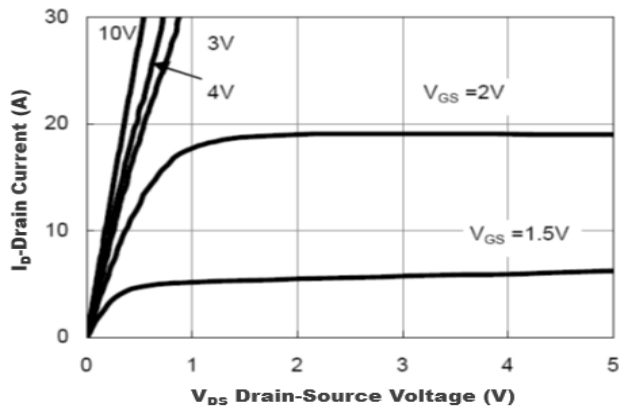


Figure1. Output Characteristics

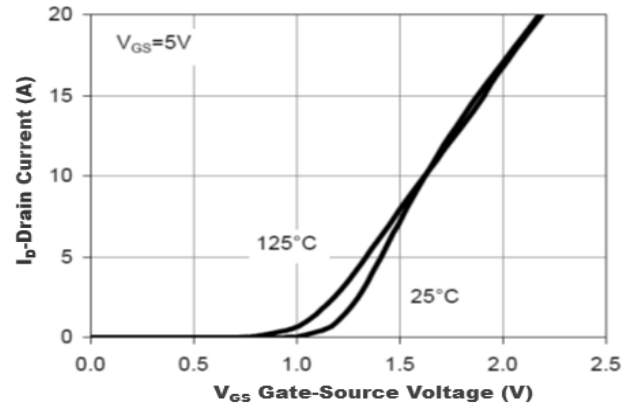


Figure2. Transfer Characteristics

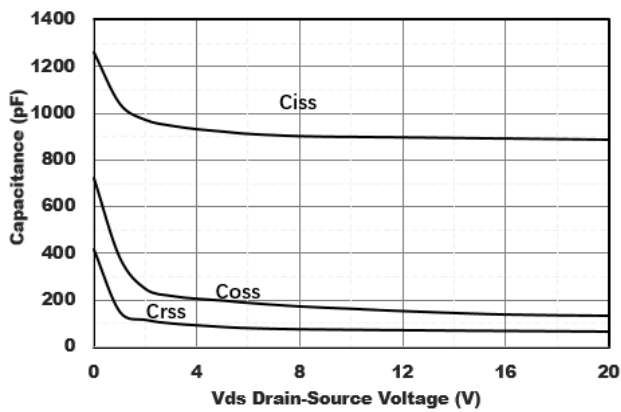


Figure3. Capacitance Characteristics

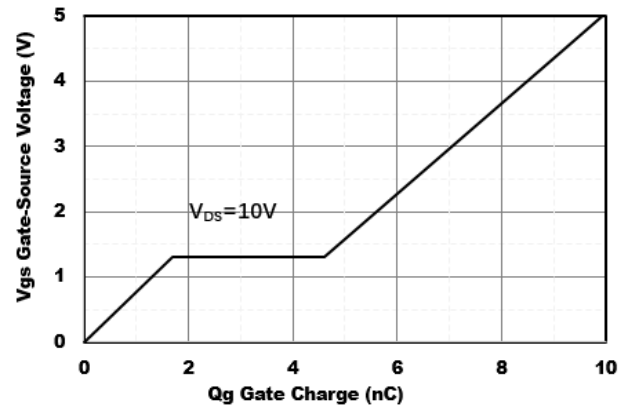


Figure4. Gate Charge

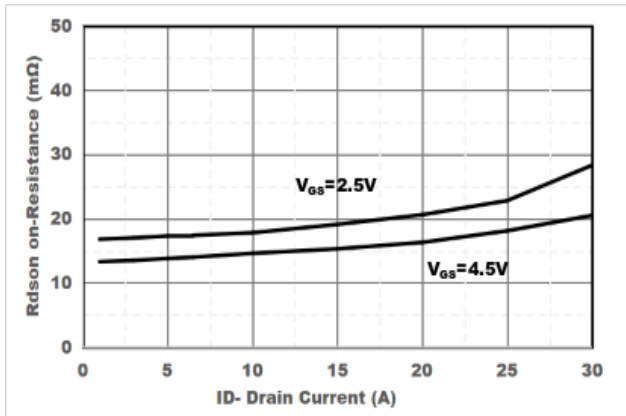


Figure5. Drain-Source on Resistance

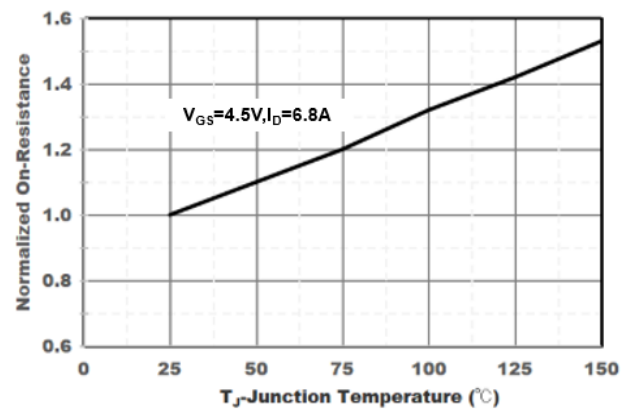


Figure6. Drain-Source on Resistance

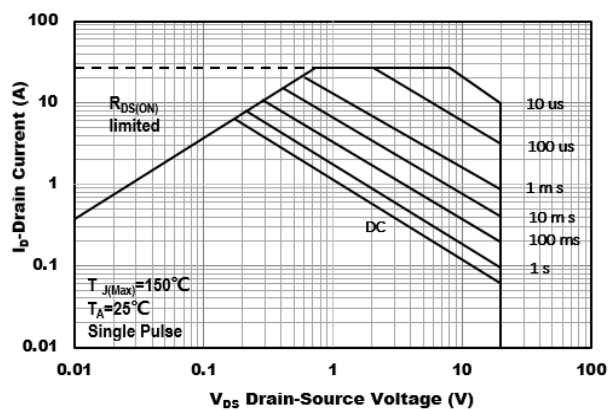


Figure7. Safe Operation Area

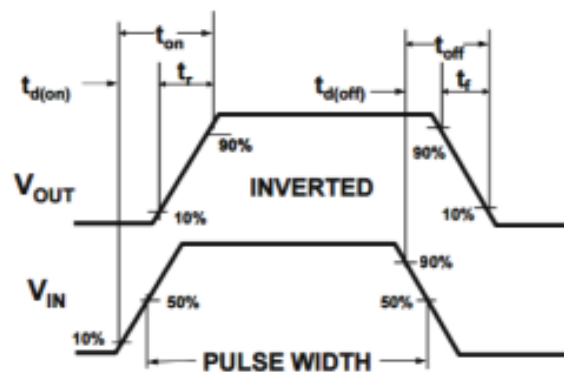
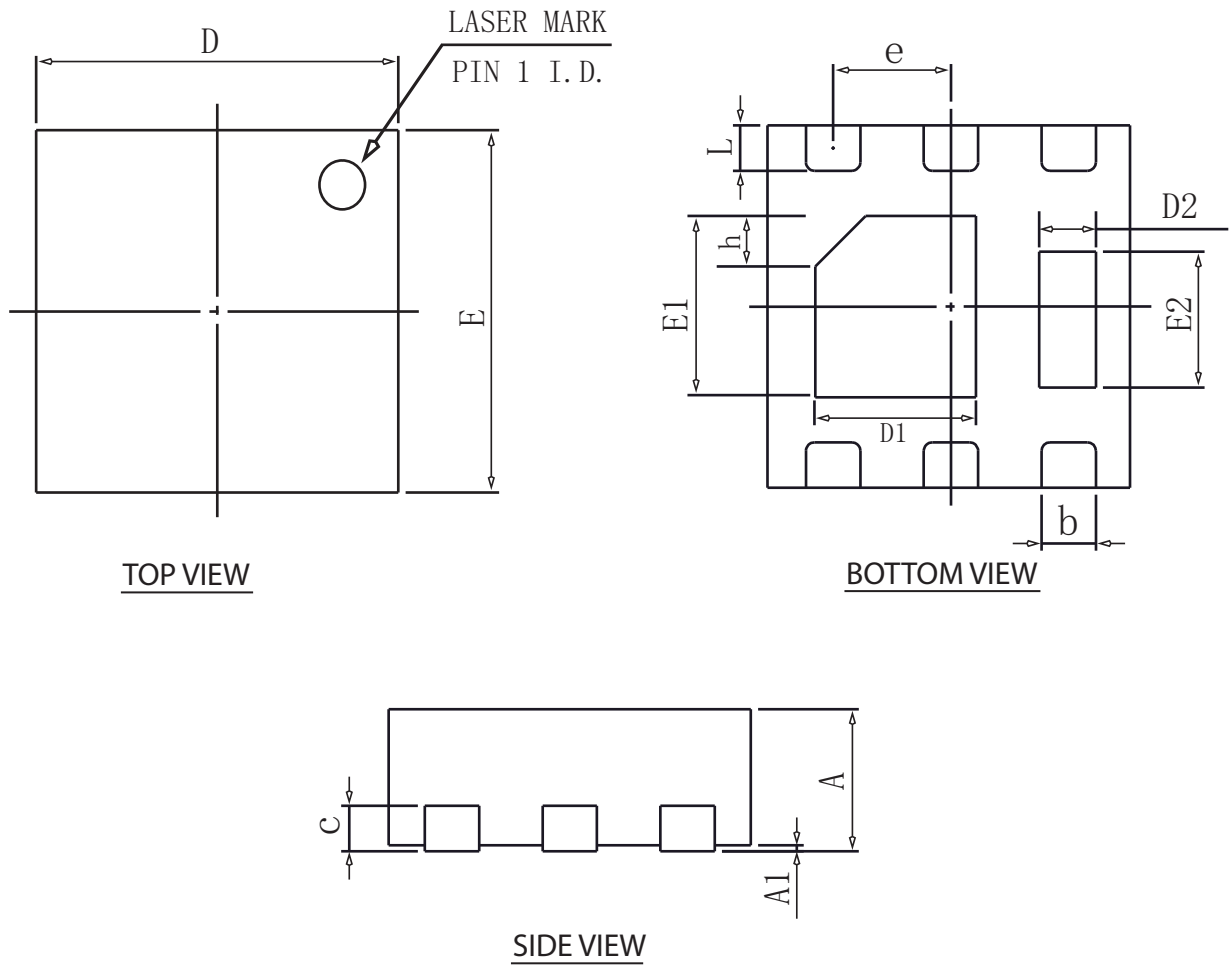


Figure8. Switching wave

DFN2X2-6L Package information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	0.413	0.452	0.493
A1	NA	0.02	0.05
b	0.20	0.27	0.34
c	0.18	0.20	0.25
D	1.95	2.00	2.07
E	1.95	2.00	2.07
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
e	0.65BSC		